

Publikationen

(2020): Characterization and Production of PCB Structures With Increased Ratio of Electromagnetic Field in Air. In: IEEE Transactions on Microwave Theory and Techniques, vol. 68, no. 6, pp. 2134-2143. DOI: 10.1109/TMTT.2020.2983934.

(2020): Cost-Effective Implementation of Air-Filled Waveguides on Printed Circuit Boards. [Invited Talk]. In: Proceedings of the IEEE Conference on Electrical Performance of Electronic Packaging and Systems (EPEPS). DOI: 10.1109/EPEPS48591.2020.9231382.

(2020): Extracting Complex PCB Substrate Permittivity from a Transmission Line using the Finite Difference Integral Method from 10 GHz - 100 GHz. [Invited Talk]. In: Proceedings of the 2020 IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP). DOI: 10.1109/IMWS-AMP49156.2020.9199738.

(2020): Design and Comparison of Filter Structures in the Millimetre Wave Frequency Range on Outer- and Inner-Layers of Organic Circuits Boards. [Invited Talk]. In: Proceedings of the 2020 European Microwave Conference (EuMC).

(2020): Simulation and Measurement of PCB Crossover Structures from DC up to 70 GHz. [Invited Talk]. In: Proceedings of the 2020 German Microwave Conference (GeMiC).

(2019): Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. Invited Talk. In: IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP), Bochum.

(2019): Simulation and Manufacturing of Low Loss PCB Structures with Additional Electromagnetic Field in Air. In: Proceedings of the IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP) [July 16-18, 2019; Bochum]. DOI: 10.1109/IMWS-AMP.2019.8880079.